

LMG3100R017 具有集成驱动器的 100V、97A GaN FET

1 特性

- 集成了 1.7mΩ GaN FET 和驱动器
- 集成了高侧电平转换和自举
- 两个 LMG3100 可构成一个半桥
 - 无需外部电平转换器
- 90V 连续 100V 脉冲式电压额定值
- 封装经过优化，便于 PCB 布局
- 5V 外部辅助电源
- 支持 3.3V 和 5V 输入逻辑电平
- 高压摆率开关，低振铃
- 栅极驱动器支持高达 10MHz 的开关频率
- 内部自举电源电压钳位，可防止 GaN FET 过驱动
- 电源轨欠压锁定保护
- 出色的传播延迟（典型值 29.5ns）和匹配（典型值 12ns）
- 低功耗
- 用于连接散热器的外露式顶部 QFN 封装

2 应用

- 降压、升压和降压/升压转换器
- LLC 转换器
- 光伏逆变器
- 电信和服务器电源
- 电机驱动器
- 电动工具
- D 类音频放大器

3 说明

LMG3100 器件是一款具有集成驱动器的 90V、97A 氮化镓 (GaN)。该器件包含一个由高频 GaN FET 驱动器驱动的 100V GaN FET。LMG3100 包含一个高侧电平转换器和自举电路，因此可以使用两个 LMG3100 器件形成半桥，而无需额外的电平转换器。

GaN FET 在功率转换方面优势极为显著，因为它们的反向恢复接近零，而且输入电容 C_{ISS} 和输出电容 C_{OSS} 都极小。所有器件均安装在一个完全无键合线的封装平台上，尽可能减少了封装寄生元件数。LMG3100 器件采用 6.5mm × 4mm × 0.89mm 无铅封装，可轻松安装在 PCB 上。

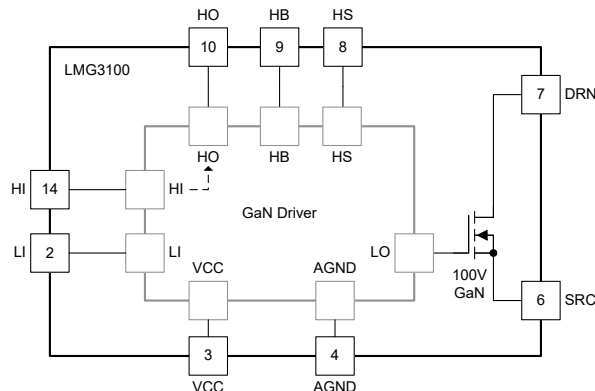
无论 VCC 电压如何，TTL 逻辑兼容输入均可支持 3.3V 和 5V 逻辑电平。专有的自举电压钳位技术确保了增强模式 GaN FET 的栅极电压处于安全的工作范围内。

该器件配有用户友好型接口且更为出色，进一步提升了分立式 GaN FET 的优势。对于需要小尺寸、高频、高效运行的应用来说，该器件是理想的解决方案。

封装信息

| 器件型号 | 封装 ⁽¹⁾ | 封装尺寸 ⁽²⁾ |
|-------------|-------------------|---------------------|
| LMG3100R017 | VBE (VQFN, 15) | 6.50mm × 4.0mm |

- 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。
- 封装尺寸（长 × 宽）为标称值，并包括引脚（如适用）。



简化版方框图



Table of Contents

| | | | |
|---|-----------|--|-----------|
| 1 特性 | 1 | 8.2 Functional Block Diagram | 10 |
| 2 应用 | 1 | 8.3 Feature Description | 11 |
| 3 说明 | 1 | 8.4 Device Functional Modes | 13 |
| 4 Pin Configuration and Functions | 3 | 9 Device and Documentation Support | 20 |
| 5 Specifications | 4 | 9.1 Documentation Support | 20 |
| 5.1 Absolute Maximum Ratings..... | 4 | 9.2 接收文档更新通知 | 20 |
| 5.2 ESD Ratings..... | 4 | 9.3 支持资源 | 20 |
| 5.3 Recommended Operating Conditions..... | 4 | 9.4 Trademarks | 20 |
| 5.4 Thermal Information | 4 | 9.5 静电放电警告 | 20 |
| 5.5 Electrical Characteristics..... | 5 | 9.6 术语表 | 20 |
| 6 Typical Characteristics | 7 | 10 Revision History | 20 |
| 7 Parameter Measurement Information | 8 | 11 Mechanical, Packaging, and Orderable Information | 21 |
| 7.1 Propagation Delay and Mismatch Measurement..... | 8 | 11.1 Package Information..... | 21 |
| 8 Detailed Description | 10 | 11.2 Tape and Reel Information..... | 25 |
| 8.1 Overview..... | 10 | | |

4 Pin Configuration and Functions

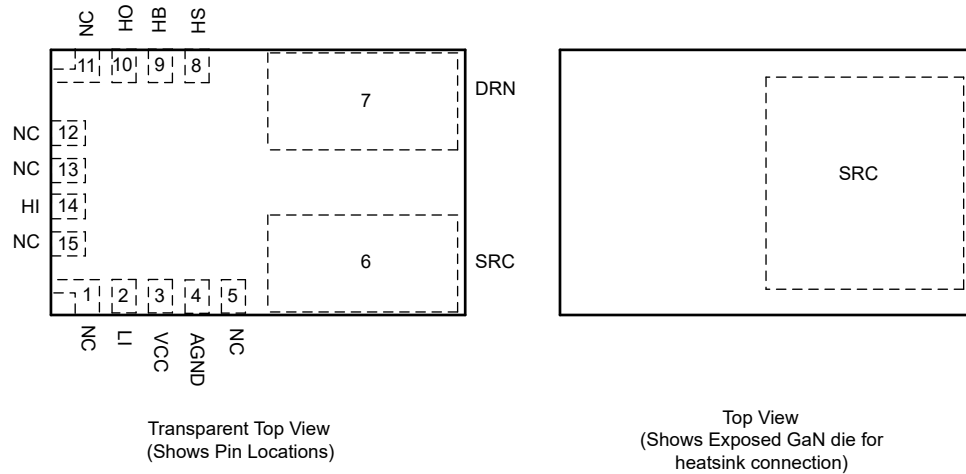


图 4-1. VBE Package, 15-Pin VQFN (Top View)

表 4-1. Pin Functions

| PIN | | I/O ⁽¹⁾ | DESCRIPTION |
|------|-------------------|--------------------|---|
| NAME | NO. | | |
| NC | 1, 5, 11 – 13, 15 | — | Not connected internally. Leave floating. |
| LI | 2 | I | Low-side gate driver control input. |
| VCC | 3 | P | 5V device power supply. |
| AGND | 4 | G | Analog ground. |
| SRC | 6 | I/O | Source of GaN FET. Internally connected to AGND. |
| DRN | 7 | I/O | Drain of GaN FET. |
| HS | 8 | P | Bootstrap voltage ground reference. |
| HB | 9 | P | High-side gate driver bootstrap rail with HS as the ground reference. |
| HO | 10 | O | Level shifted high-side gate driver control input. |
| HI | 14 | I | High-side gate driver control input. |

(1) I = Input, O = Output, G = Ground, P = Power

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

| | MIN | MAX | UNIT |
|--|------|-----|------|
| DRN to SRC | -5 | 100 | V |
| DRN to SRC (pulsed, 100-ms max duration) ⁽²⁾ | | 120 | V |
| HB to AGND | -0.3 | 100 | V |
| HS to AGND | -5 | 93 | V |
| HI to AGND | -0.3 | 6 | V |
| LI to AGND | -0.3 | 6 | V |
| VCC to AGND | -0.3 | 6 | V |
| HB to HS | -0.3 | 6 | V |
| HB to VCC | 0 | 93 | V |
| IOOUT from DRN pin (Continuous), T _J = 25°C | | 97 | A |
| IOOUT from DRN pin (Pulsed, 300 μs), T _J = 25°C | | 350 | A |
| Junction Temperature, T _J | -40 | 150 | °C |
| Storage Temperature, T _{stg} | -40 | 150 | °C |

- (1) Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute Maximum Ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If used outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
- (2) GaN FET can withstand 1000 pulses up to 120V of 100ms duration and less than 1% duty cycle over its lifetime.

5.2 ESD Ratings

| | | | VALUE | UNIT |
|--------------------|-------------------------|--|-------|------|
| V _(ESD) | Electrostatic Discharge | Human-body model (HBM), per ANSI/ESDA/ JEDEC JS-001 ⁽¹⁾ | ±500 | V |
| | | Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾ | ±500 | V |

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

| | MIN | NOM | MAX | UNIT |
|----------------|-----|-----|------|------|
| VCC | 4.5 | 5 | 5.25 | V |
| LI or HI Input | 0 | | 6 | V |
| HS, DRN | -5 | | 90 | V |

5.4 Thermal Information

| THERMAL METRIC ⁽¹⁾ | | LMG2100 | UNIT |
|-------------------------------|--|---------|------|
| | | QFN | |
| | | 9 PINS | |
| R _{θJA} | Junction-to-ambient thermal resistance | 36 | °C/W |
| R _{θJC(top)} | Junction-to-case (top) thermal resistance | 0.4 | |
| R _{θJB} | Junction-to-board thermal resistance | 3 | °C/W |
| ψ _{JT} | Junction-to-top characterization parameter | 1.8 | °C/W |

5.4 Thermal Information (续)

| THERMAL METRIC ⁽¹⁾ | | LMG2100 | UNIT |
|-------------------------------|--|---------|------|
| | | QFN | |
| | | 9 PINS | |
| ψ_{JB} | Junction-to-board characterization parameter | 6 | °C/W |

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

5.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|---------------------------------|---|--|---------------|------|-------|------------|
| SUPPLY CURRENTS | | | | | | |
| I_{CC} | VCC Quiescent Current | LI = HI = 0V, VCC = 5V | | 0.08 | 0.125 | mA |
| I_{CC} | VCC Quiescent Current | LI=VCC=5V, HI=0V | | 0.17 | 5 | mA |
| I_{CCO} | Total VCC Operating Current | f = 500 kHz, 50% Duty cycle, $V_{IN} = 48V$ | | 10 | 15.0 | mA |
| I_{HB} | HB Quiescent Current | LI = HI = 0V, VCC = 5V, HB-HS = 4.6V | | 0.1 | 0.150 | mA |
| I_{HB} | HB Quiescent Current | LI=0V, HI=VCC=5V, HB-HS=4.6V, $V_{IN}=48V$ | | 0.16 | 0.25 | mA |
| INPUT PINS | | | | | | |
| V_{IH} | High-Level Input Voltage Threshold | Rising Edge | 1.87 | 2.06 | 2.22 | V |
| V_{IL} | Low-Level Input Voltage Threshold | Falling Edge | 1.48 | 1.66 | 1.76 | V |
| V_{HYS} | Hysteresis between rising and falling threshold | | | 350 | | mV |
| R_I | Input pull down resistance | | 100 | 200 | 300 | k Ω |
| OUTPUT PINS | | | | | | |
| V_{OL} | Low level output voltage | $I_{OL} = 10$ mA | | | 0.01 | V |
| V_{OH} | High level output voltage | $I_{OL} = -10$ mA | $V_{HB}-0.03$ | | | V |
| UNDER VOLTAGE PROTECTION | | | | | | |
| V_{CCR} | VCC Rising edge threshold | Rising | 3.2 | 3.8 | 4.5 | V |
| V_{CCF} | VCC Falling edge threshold | | 3.0 | 3.6 | 4.3 | V |
| $V_{CC(hyst)}$ | VCC UVLO threshold hysteresis | | | 217 | | mV |
| V_{HBR} | HB Rising edge threshold | Rising | 2.5 | 3.2 | 3.9 | V |
| V_{HBF} | HB Falling edge threshold | | 2.3 | 3.0 | 3.7 | V |
| $V_{HB(hyst)}$ | HB UVLO threshold hysteresis | | | 224 | | mV |
| BOOTSTRAP DIODE | | | | | | |
| V_{DL} | Low-Current forward voltage | $I_{VDD-HB} = 100\mu A$ | | 0.45 | 0.65 | V |
| V_{DH} | High current forward voltage | $I_{VDD-HB} = 100$ mA | | 0.9 | 1.0 | V |
| R_D | Dynamic Resistance | $I_{VDD-HB} = 100$ mA | | 1.85 | | Ω |
| | HB-HS Clamp | Regulation Voltage | 4.65 | 5 | 5.2 | V |
| t_{BS} | Bootstrap diode reverse recovery time | $I_F = 100$ mA, $I_R = 100$ mA | | 40 | | ns |
| Q_{RR} | Bootstrap diode reverse recovery charge | $V_{VIN} = 50$ V | | 2 | | nC |
| POWER STAGE R017 | | | | | | |
| $R_{DS(ON)}$ | GaN FET on-resistance | LI=VCC=5V, HI=0V, $I(DRN-SRC)=30A$, $T_J = 25^\circ C$ | | 1.7 | 2.2 | m Ω |
| V_{SD} | GaN 3rd quadrant conduction drop | $I_{SD} = 500$ mA, $V_{VCC} = 5$ V, HI = LI = 0V | | 1.5 | | V |
| $I_{L-DRN-SRC}$ | Leakage from DRN to SRC when the GaN FET is off | DRN = 80V, HI = LI = 0V, $V_{VCC} = 5V$, $T_J=25^\circ C$ | | 12 | 300 | μA |
| C_{OSS} | Output Capacitance of GaN FET | $V_{DS}=50V$, $V_{GS}= 0V$ (HI = LI = 0V) | | 880 | 980 | pF |
| $C_{OSS(ER)}$ | Output Capacitance of GaN FET - Energy Related | $V_{DS}=0$ to 50V, $V_{GS}= 0V$ (HI = LI = 0V) | | 1058 | | pF |
| $C_{OSS(TR)}$ | Output Capacitance of GaN FET - Time Related | $V_{DS}=0$ to 50V, $V_{GS}= 0V$ (HI = LI = 0V) | | 1422 | | pF |

5.5 Electrical Characteristics (续)

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|-------------|---|---|-----|------|-----|------|
| Q_G | Total Gate Charge of high side or low side HEMT | $V_{DS}=50V$, $I_D=30A$, $V_{GS}=5V$ | | 20.3 | 29 | nC |
| Q_{GD} | Gate to Drain Charge of high side or low side HEMT | $V_{DS}=50V$, $I_D=16A$ | | 1.8 | | nC |
| Q_{GS} | Gate to Source Charge of high side or low side HEMT | $V_{DS}=50V$, $I_D=16A$ | | 6 | | nC |
| Q_{OSS} | Output Charge | $V_{DS}=50V$, $I_D=16A$ | | 76 | 88 | nC |
| Q_{RR} | Source to Drain Reverse Recovery Charge | Not including internal driver bootstrap diode | | 0 | | nC |
| t_{HIPLH} | Propagation delay: HI Rising ⁽²⁾ | $LI=0V$, $VCC=5V$, $HB-HS=5V$, $VIN=48V$ | | 55 | 90 | ns |
| t_{HIPHL} | Propagation delay: HI Falling ⁽²⁾ | $LI=0V$, $VCC=5V$, $HB-HS=5V$, $VIN=48V$ | | 55 | 90 | ns |
| t_{LPLH} | Propagation delay: LI Rising ⁽²⁾ | $HI=0V$, $VCC=5V$, $HB-HS=5V$, $VIN=48V$ | | 29.5 | 50 | ns |
| t_{LPHL} | Propagation delay: LI Falling ⁽²⁾ | $HI=0V$, $VCC=5V$, $HB-HS=5V$, $VIN=48V$ | | 29.5 | 50 | ns |
| t_{MON} | Delay Matching: LI high & HI low ⁽²⁾ | | | 25 | 40 | ns |
| t_{MOFF} | Delay Matching: LI low & HI high ⁽²⁾ | | | 25 | 40 | ns |
| t_{PW} | Minimum Input Pulse Width that Changes the Output | | | 10 | | ns |

(1) Parameters that show only a typical value are determined by design and may not be tested in production

(2) See *Propagation Delay and Mismatch Measurement* section

6 Typical Characteristics

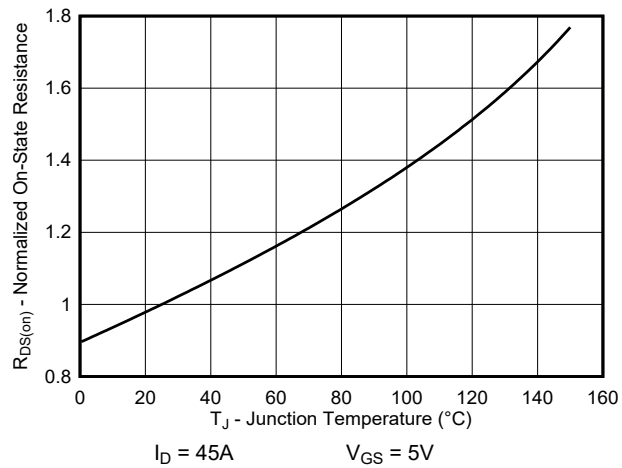


图 6-1. Normalized On-State Resistance vs Junction Temperature

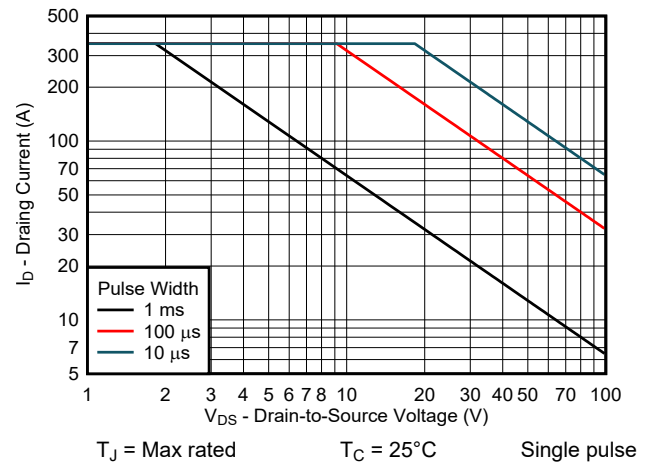


图 6-2. Safe Operating Area

7 Parameter Measurement Information

7.1 Propagation Delay and Mismatch Measurement

Figure 7-1 shows the typical test setup used to measure the propagation mismatch. As the gate drives are not accessible, pullup and pulldown resistors in this test circuit are used to indicate when the low-side GaN FET turns ON and the high-side GaN FET turns OFF and vice versa to measure the t_{MON} and t_{MOFF} parameters. Resistance values used in this circuit for the pullup and pulldown resistors are in the order of $1\text{ k}\Omega$; the current sources used are 2 A .

Figure 7-2 through Figure 7-5 show propagation delay measurement waveforms. For turnon propagation delay measurements, the current sources are not used. For turnoff time measurements, the current sources are set to 2A, and a voltage clamp limit is also set, referred to as $V_{IN(CLAMP)}$. When measuring the high-side component turnoff delay, the current source across the high-side FET is turned on, the current source across the low-side FET is off, HI transitions from high-to-low, and output voltage transitions from V_{IN} to $V_{IN(CLAMP)}$. Similarly, for low-side component turnoff propagation delay measurements, the high-side component current source is turned off, and the low-side component current source is turned on, LI transitions from high to low and the output transitions from GND potential to $V_{IN(CLAMP)}$. The time between the transition of LI and the output change is the propagation delay time.

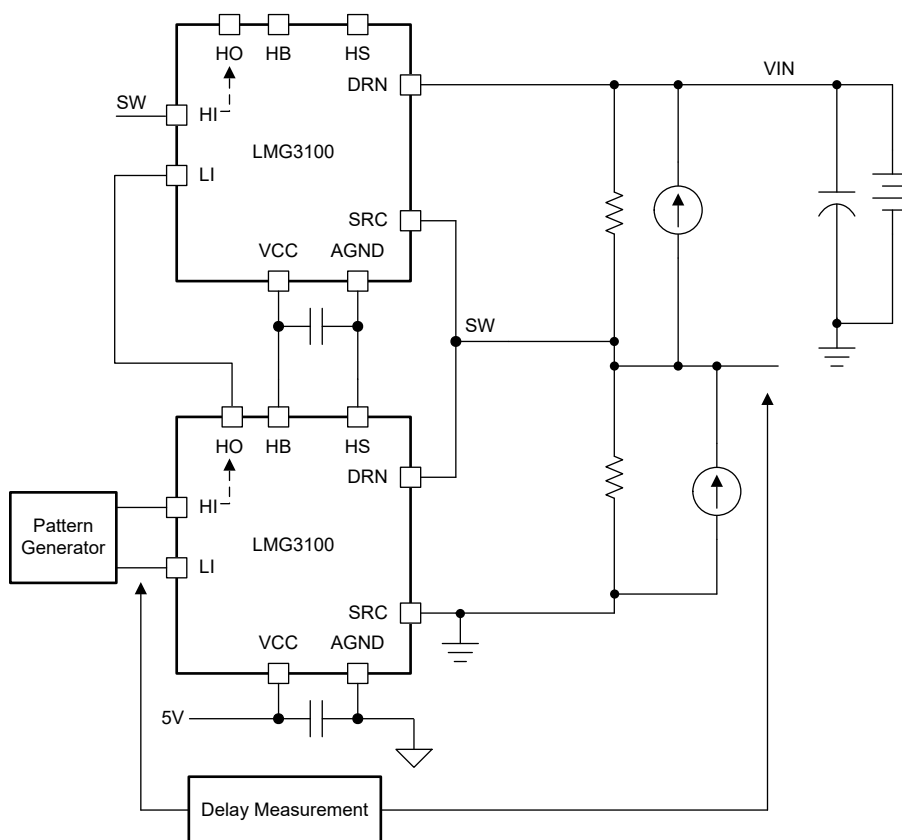


图 7-1. Propagation Delay and Propagation Mismatch Measurement

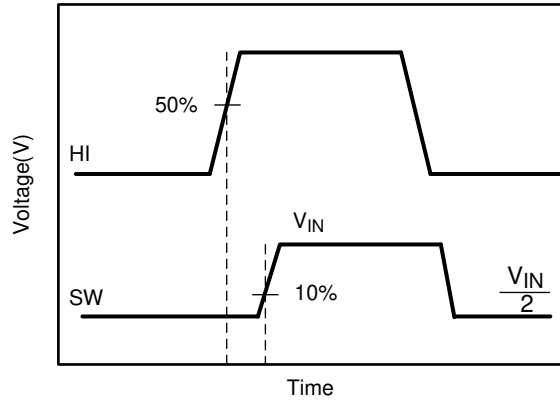


图 7-2. High-Side Gate Driver Turnon

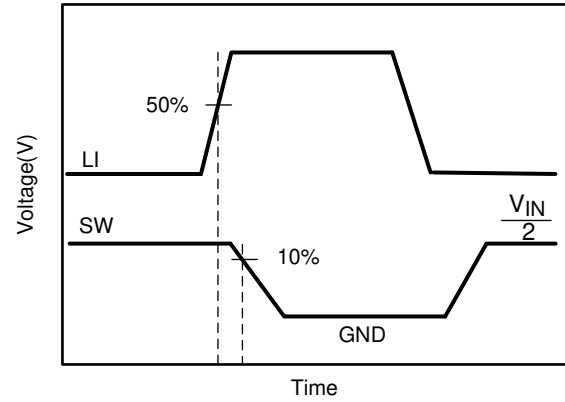


图 7-3. Low-Side Gate Driver Turnon

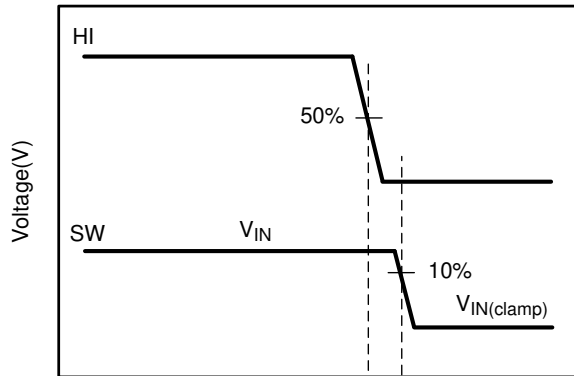


图 7-4. High-Side Gate Driver Turnoff

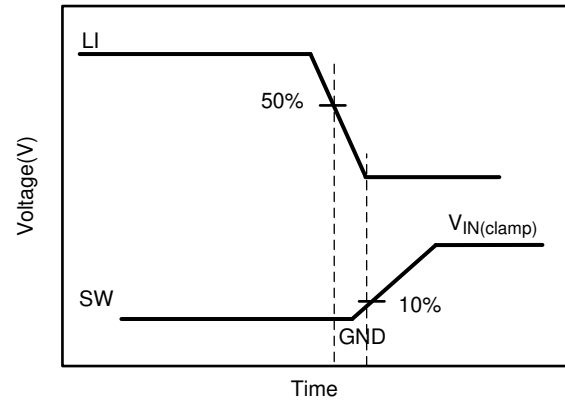


图 7-5. Low-Side Gate Driver Turnoff

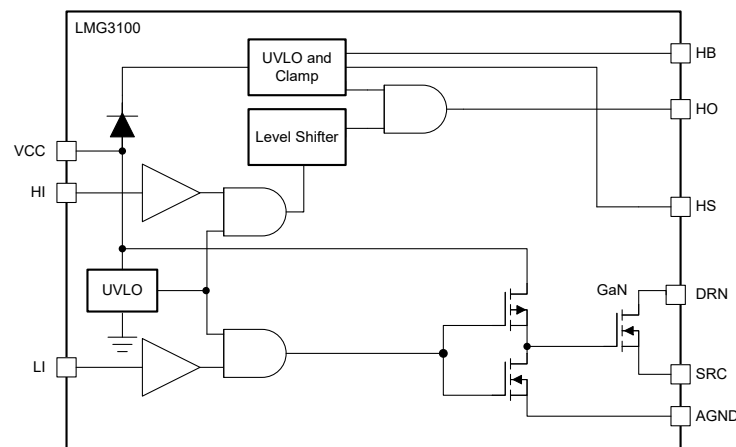
8 Detailed Description

8.1 Overview

节 8.2 shows the LMG3100 GaN FET with gate driver, high-side level shift and bootstrap circuit, which includes built-in UVLO protection circuitry and an overvoltage clamp circuitry. The clamp circuitry limits the bootstrap refresh operation to ensure that the high-side gate driver overdrive does not exceed 5.4V. The device integrates a 1.7mΩ GaN FET, with the possibility of using two LMG3100 to form a half-bridge without external level shifter. The device can be used in many isolated and non-isolated topologies allowing very simple integration. The drive strengths for turnon and turnoff are optimized to ensure high voltage slew rates without causing any excessive ringing on the gate or power loop.

8.2 Functional Block Diagram

The functional block diagram of the LMG3100 device with integrated GaN FET and driver, high-side level shift, and bootstrap circuit.



8.3 Feature Description

The LMG3100 device brings ease of designing high power density boards without the need for underfill while maintaining creepage and clearance requirements. The propagation delays between the high-side gate driver and low-side gate driver are matched to allow very tight control of dead time. Controlling the dead time is critical in GaN-based applications to maintain high efficiency. HI and LI can be independently controlled to minimize the third quadrant conduction of the low-side FET for hard switched buck converters. A very small propagation mismatch between the HI and LI to the drivers for both the falling and rising thresholds ensures dead times of < 20 ns. Co-packaging the GaN FET half-bridge with the driver ensures minimized common source inductance. This minimized inductance has a significant performance impact on hard-switched topologies.

The built-in bootstrap circuit with clamp prevents the high-side gate drive from exceeding the GaN FETs maximum gate-to-source voltage (V_{gs}) without any additional external circuitry. The built-in driver has an undervoltage lockout (UVLO) on the VDD and bootstrap (HB-HS) rails. When the voltage is below the UVLO threshold voltage, the device ignores both the HI and LI signals to prevent the GaN FETs from being partially turned on. Below UVLO, if there is sufficient voltage ($V_{VCC} > 2.5$ V), the driver actively pulls the high-side and low-side gate driver output low. The UVLO threshold hysteresis of 200 mV prevents chattering and unwanted turnon due to voltage spikes. Use an external VCC bypass capacitor with a value of 1 μ F or higher. TI recommends a size of 0402 to minimize trace length to the pin. Place the bypass and bootstrap capacitors as close as possible to the device to minimize parasitic inductance.

8.3.1 Control Inputs

The LMG3100's inputs pins are independently controlled with TTL input thresholds and can support 3.3-V and 5-V logic levels regardless of the VCC voltage.

In order to allow flexibility to optimize deadtime according to design needs, the LMG3100 does not implement an overlap protection functionality. If both HI and LI are asserted, both the high-side and low-side GaN FETs are turned on. Careful consideration must be applied to the control inputs in order to avoid a shoot-through condition.

8.3.2 Start-up and UVLO

The LMG3100 has an UVLO on both the V_{CC} and HB (bootstrap) supplies. When the V_{CC} voltage is below the threshold voltage of 3.8 V, both the HI and LI inputs are ignored, to prevent the GaN FETs from being partially turned on. Also, if there is insufficient V_{CC} voltage, the UVLO actively pulls the high- and low-side GaN FET gates low. When the HB to HS bootstrap voltage is below the UVLO threshold of 3.2 V, only the high-side GaN FET gate is pulled low. Both UVLO threshold voltages have 200 mV of hysteresis to avoid chattering.

表 8-1. V_{CC} UVLO Feature Logic Operation

| CONDITION ($V_{HB-HS} > V_{HBR}$ for all cases below) | HI | LI | SW |
|--|----|----|------|
| $V_{CC} - V_{SS} < V_{CCR}$ during device start-up | H | L | Hi-Z |
| $V_{CC} - V_{SS} < V_{CCR}$ during device start-up | L | H | Hi-Z |
| $V_{CC} - V_{SS} < V_{CCR}$ during device start-up | H | H | Hi-Z |
| $V_{CC} - V_{SS} < V_{CCR}$ during device start-up | L | L | Hi-Z |
| $V_{CC} - V_{SS} < V_{CCR} - V_{CC(hyst)}$ after device start-up | H | L | Hi-Z |
| $V_{CC} - V_{SS} < V_{CCR} - V_{CC(hyst)}$ after device start-up | L | H | Hi-Z |
| $V_{CC} - V_{SS} < V_{CCR} - V_{CC(hyst)}$ after device start-up | H | H | Hi-Z |
| $V_{CC} - V_{SS} < V_{CCR} - V_{CC(hyst)}$ after device start-up | L | L | Hi-Z |

表 8-2. V_{HB-HS} UVLO Feature Logic Operation

| CONDITION ($V_{CC} > V_{CCR}$ for all cases below) | HI | LI | SW |
|---|----|----|------|
| $V_{HB-HS} < V_{HBR}$ during device start-up | H | L | Hi-Z |
| $V_{HB-HS} < V_{HBR}$ during device start-up | L | H | PGND |
| $V_{HB-HS} < V_{HBR}$ during device start-up | H | H | PGND |
| $V_{HB-HS} < V_{HBR}$ during device start-up | L | L | Hi-Z |

表 8-2. V_{HB-HS} UVLO Feature Logic Operation (续)

| CONDITION ($V_{CC} > V_{CCR}$ for all cases below) | HI | LI | SW |
|--|----|----|------|
| $V_{HB-HS} < V_{HBR} - V_{HB(hyst)}$ after device start-up | H | L | Hi-Z |
| $V_{HB-HS} < V_{HBR} - V_{HB(hyst)}$ after device start-up | L | H | PGND |
| $V_{HB-HS} < V_{HBR} - V_{HB(hyst)}$ after device start-up | H | H | PGND |
| $V_{HB-HS} < V_{HBR} - V_{HB(hyst)}$ after device start-up | L | L | Hi-Z |

8.3.3 Bootstrap Supply Voltage Clamping

The high-side bias voltage is generated using a bootstrap technique and is internally clamped at 5 V (typical). This clamp prevents the gate voltage from exceeding the maximum gate-source voltage rating of the enhancement-mode GaN FETs.

8.3.4 Level Shift

The level-shift circuit is the interface from the high-side input HI to the high-side driver stage, which is referenced to the switch node (HS). The level shift allows control of the high-side GaN FET gate driver output, which is referenced to the HS pin and provides excellent delay matching with the low-side driver.

8.4 Device Functional Modes

The LMG3100 operates in normal mode and UVLO mode. See [节 8.3.2](#) for information on UVLO operation mode. In the normal mode, the output state is dependent on the states of the HI and LI pins. [表 8-3](#) lists the output states for different input pin combinations. Note that when both HI and LI are asserted, both GaN FETs in the power stage are turned on. Careful consideration must be applied to the control inputs in order to avoid this state, as it will result in a shoot-through condition, which can permanently damage the device.

表 8-3. Truth Table

| HI | LI | HIGH-SIDE GaN FET | LOW-SIDE GaN FET | SW |
|----|----|-------------------|------------------|-------|
| L | L | OFF | OFF | Hi-Z |
| L | H | OFF | ON | PGND |
| H | L | ON | OFF | VIN |
| H | H | ON | ON | - - - |

Application and Implementation

备注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

The LMG3100 GaN power stage is a versatile building block for various types of high-frequency, switch-mode power applications. The high-performance gate driver IC integrated in the package helps minimize the parasitics and results in extremely fast switching of the GaN FETs. The device design is highly optimized for synchronous buck converters and other half-bridge configurations.

9.2 Typical Application

[图 9-1](#) shows a synchronous buck converter application using a digital PWM controller. The control signal for the high-side LMG3100 provided by the digital controller is level shifted through the low-side LMG3100, to complete the half-bridge without using an additional level shifter. It is critical to optimize the power loop (loop impedance from VIN capacitor to PGND). Having a high power loop inductance causes significant ringing in the SW node and also causes the associated power loss.

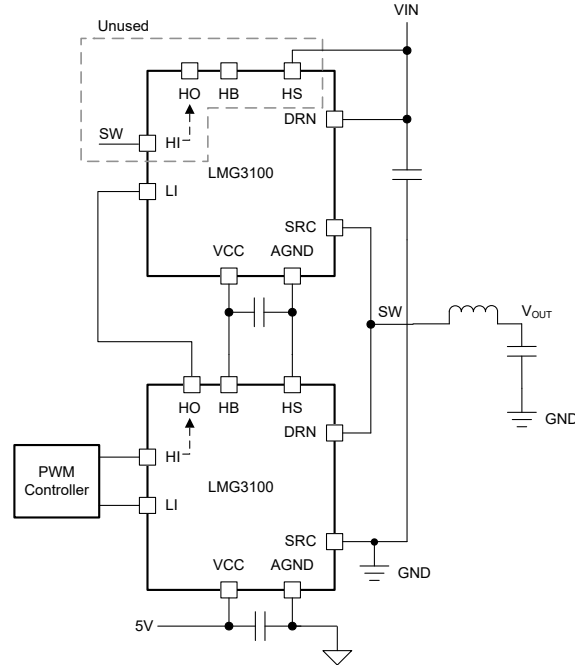


图 9-1. Typical Connection Diagram For a Synchronous Buck Converter

9.2.1 Design Requirements

When designing a synchronous buck converter application that incorporates the LMG3100 power stage, some design considerations must be evaluated first to make the most appropriate selection. Among these considerations are the input voltages, passive components, operating frequency, and controller selection. 表 9-1 shows some sample values for a typical application. See [节 Power Supply Recommendations](#), [节 9.3](#), and [节 9.2.2.5](#) for other key design considerations for the LMG3100.

表 9-1. Design Parameters

| PARAMETER | SAMPLE VALUE |
|--|------------------|
| Half-bridge input supply voltage, V_{IN} | 48 V |
| Output voltage, V_{OUT} | 12 V |
| Output current | 8 A |
| V_{HB-HS} bootstrap capacitor | 0.3 μ F, X5R |
| Switching frequency | 1 MHz |
| Dead time | 8 ns |
| Inductor | 4.7 μ H |
| Controller | LM5148 |

9.2.2 Detailed Design Procedure

This procedure outlines the design considerations of LMG3100 in a synchronous buck converter. For additional design help, see [节 9.1.1](#).

9.2.2.1 V_{CC} Bypass Capacitor

The V_{CC} bypass capacitor provides the gate charge for the low-side and high-side transistors and to absorb the reverse recovery charge of the bootstrap diode. The required bypass capacitance can be calculated with [方程式 1](#).

$$C_{VCC} = (2 \times Q_G + Q_{RR}) / \Delta V \quad (1)$$

Q_G is the individual and equal gate charge of the high-side and low-side GaN FETs. Q_{RR} is the reverse recovery charge of the bootstrap diode. ΔV is the maximum allowable voltage drop across the bypass capacitor. A 1- μF or larger value, good-quality, ceramic capacitor is recommended. Place the bypass capacitor as close as possible to the V_{CC} and AGND pins of the device to minimize the parasitic inductance.

9.2.2.2 Bootstrap Capacitor

The bootstrap capacitor provides the gate charge for the high-side gate drive, dc bias power for HB UVLO circuit, and the reverse recovery charge of the bootstrap diode. The required bypass capacitance can be calculated using 方程式 2.

$$C_{BST} = (Q_G + Q_{RR} + I_{CC} * t_{ON(max)}) / \Delta V \quad (2)$$

where

- I_{CC} is the quiescent current of the high side device
- $t_{ON(max)}$ is the maximum on-time period of the high-side gate driver
- Q_{RR} is the reverse recovery charge of the bootstrap diode
- Q_G is the gate charge of the high-side GaN FET
- ΔV is the permissible ripple in the bootstrap capacitor (< 100 mV, typical)

A 0.3- μF , 16-V, 0402 ceramic capacitor is suitable for most applications. Place the bootstrap capacitor as close as possible to the HB and HS pins.

9.2.2.3 Slew Rate Control

图 9-2 shows a switching application where the slew rate on the switch node may be controlled by using resistors R_{VCCCL} and R_{VCCCH} . R_{VCCCL} may be used to slow down the turn-on of the Low Side GaN FET (for example, in a buck converter), and R_{VCCCH} may be used to slow down the turn-on of the High Side GaN FET (for example, in a boost converter). Using these resistors allows the system engineer to optimize the tradeoff between higher efficiency (faster slew rates) and lower ringing (slower slew rates).

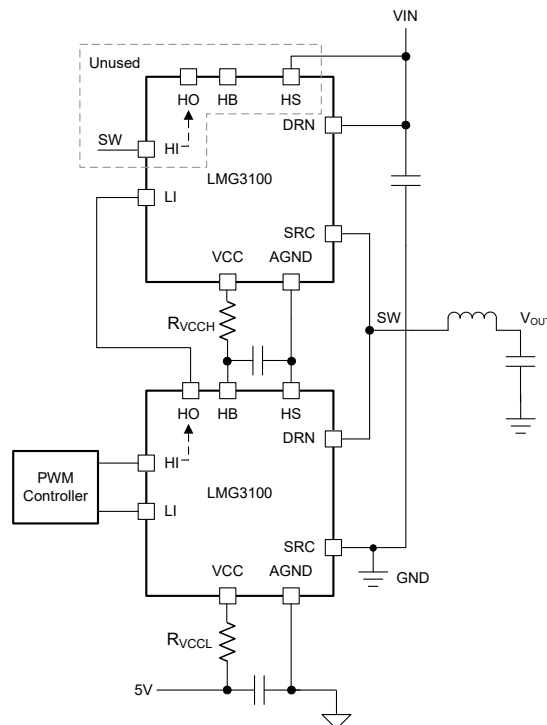


图 9-2. Slew Rate Control with R_{VCCCL} and R_{VCCCH} Resistors

9.2.2.4 Use With Analog Controllers

图 9-3 shows a synchronous buck converter application using an analog controller that provides level-shifted high-side control with the switch node as reference. The analog controller also generates the bootstrap voltage. In this use case, the level-shifted high-side control output, HO, from the controller may be directly connected to the input pin, LI, of the high-side LMG3100. The in-built level shifter and boot-strap circuits of the low-side LMG3100 are left unused.

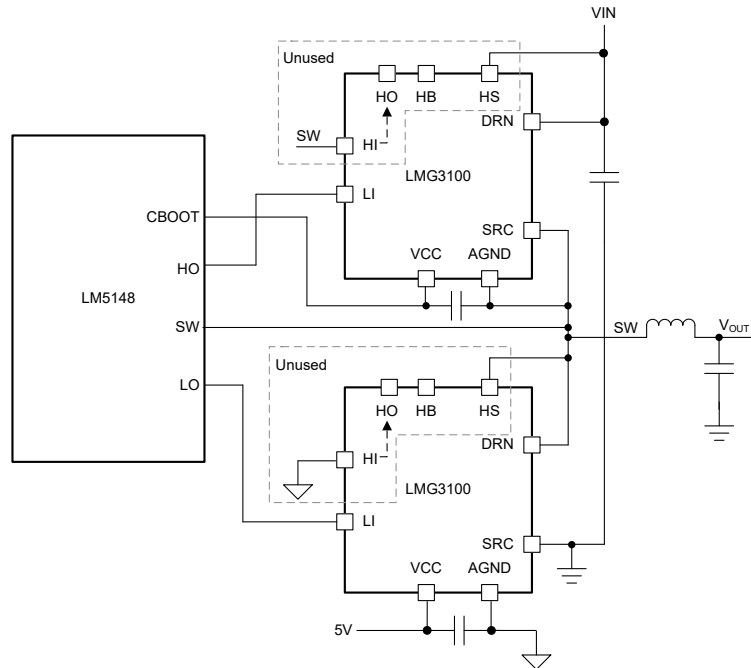


图 9-3. Use With Analog Controllers That Have In-built Level-shifting

9.2.2.5 Power Dissipation

Ensure that the power loss in the driver and the GaN FETs is maintained below the maximum power dissipation limit of the package at the operating temperature. The smaller the power loss in the driver and the GaN FETs, the higher the maximum operating frequency that can be achieved in the application. The total power dissipation of the LMG3100 device is the sum of the gate driver losses, the bootstrap diode power loss and the switching and conduction losses in the FETs.

The gate driver losses are incurred by charge and discharge of the capacitive load. It can be approximated using [方程式 3](#).

$$P = 2 \times Q_G \times V_{CC} \times f_{SW} \quad (3)$$

where

- Q_G is the gate charge
- V_{CC} is the bias supply
- f_{SW} is the switching frequency

There are some additional losses in the gate drivers due to the internal CMOS stages used to buffer the outputs.

The bootstrap diode power loss is the sum of the forward bias power loss that occurs while charging the bootstrap capacitor and the reverse bias power loss that occurs during reverse recovery. Because each of these events happens once per cycle, the diode power loss is proportional to the operating frequency. Higher input voltages (V_{IN}) to the half bridge also result in higher reverse recovery losses.

The power losses due to the GaN FETs can be divided into conduction losses and switching losses. Conduction losses are resistive losses and can be calculated using [方程式 4](#).

$$P_{COND} = \left[(I_{RMS(HS)})^2 \times R_{DS(on)HS} \right] + \left[(I_{RMS(LS)})^2 \times R_{DS(on)LS} \right] \quad (4)$$

where

- $R_{DS(on)HS}$ is the high-side GaN FET on-resistance
- $R_{DS(on)LS}$ is the low-side GaN FET on-resistance
- $I_{RMS(HS)}$ is the high-side GaN FET RMS current
- $I_{RMS(LS)}$ and low-side GaN FET RMS current

The switching losses can be computed to a first order using , t_{TR} can be approximated by dividing V_{IN} by 25V/ns, which is a conservative estimate of the switched node slew rate. [方程式 5](#).

$$P_{SW} = V_{IN} \times I_{OUT} \times t_{TR} \times f_{SW} + V_{IN} \times V_{IN} \times C_{OSS(ER)} \times f_{SW} \quad (5)$$

where

- t_{TR} is sum of the switch node transition times from ON to OFF and from OFF to ON
- $C_{OSS(ER)}$ is the output capacitance of each GaN FET

Note that the low-side FET does not suffer from this loss. The third quadrant loss in the low-side device is ignored in this first order loss calculation.

As described previously, switching frequency has a direct effect on device power dissipation. Although the gate driver of the LMG3100 device is capable of driving the GaN FETs at frequencies up to 10MHz, careful consideration must be applied to ensure that the running conditions for the device meet the recommended operating temperature specification. Specifically, hard-switched topologies tend to generate more losses and self-heating than soft-switched applications.

The sum of the driver loss, the bootstrap diode loss, and the switching and conduction losses in the GaN FETs is the total power loss of the device. Careful board layout with an adequate amount of thermal vias close to the power pads (VIN and PGND) allows optimum power dissipation from the package. A top-side mounted heat sink with airflow can also improve the package power dissipation.

Power Supply Recommendations

The recommended bias supply voltage range for LMG3100 is from 4.75 V to 5.25 V. The lower end of this range is governed by the internal undervoltage lockout (UVLO) protection feature of the V_{CC} supply circuit. The upper end of this range is driven by the 6 V absolute maximum voltage rating of V_{CC} . Note that the gate voltage of the low-side GaN FET is not clamped internally. Hence, it is important to keep the V_{CC} bias supply within the recommended operating range to prevent exceeding the low-side GaN transistor gate breakdown voltage.

The UVLO protection feature also involves a hysteresis function. This means that once the device is operating in normal mode, if the V_{CC} voltage drops, the device continues to operate in normal mode as far as the voltage drop does not exceeds the hysteresis specification, $V_{CC(hyst)}$. If the voltage drop is more than hysteresis specification, the device shuts down. Therefore, while operating at or near the 4.5 V range, the voltage ripple on the auxiliary power supply output must be smaller than the hysteresis specification of LMG3100 to avoid triggering device-shutdown.

Place a local bypass capacitor between the VDD and VSS pins. This capacitor must be located as close as possible to the device. A low ESR, ceramic surface-mount capacitor is recommended. TI recommends using 2 capacitors across VDD and GND: a 100 nF ceramic surface-mount capacitor for high frequency filtering placed very close to VDD and GND pin, and another surface-mount capacitor, 220 nF to 10 μ F, for IC bias requirements.

9.3 Layout

9.3.1 Layout Guidelines

To maximize the efficiency benefits of fast switching, it is extremely important to optimize the board layout such that the power loop impedance is minimal. When using a multilayer board (more than 2 layers), power loop parasitic impedance is minimized by having the return path to the input capacitor (between VIN and PGND), small and directly underneath the first layer as shown in 图 9-4 and 图 9-5. Loop inductance is reduced due to flux cancellation as the return current is directly underneath and flowing in the opposite direction.

Insufficient attention to the above power loop layout guidelines can result in excessive overshoot and undershoot on the switch node.

It is also critical that the VCC capacitors and the bootstrap capacitors are as close as possible to the device and in the first layer. Carefully consider the AGND connection of LMG3100 device. It must NOT be directly connected to PGND so that PGND noise does not directly shift AGND and cause spurious switching events due to noise injected in HI and LI signals.

9.3.2 Layout Examples

Placements shown in 图 9-4 and in the cross section of 图 9-5 show the suggested placement of the device with respect to sensitive passive components, such as VIN, bootstrap capacitors (HS and HB) and VSS capacitors. Use appropriate spacing in the layout to reduce creepage and maintain clearance requirements in accordance with the application pollution level. Inner layers if present can be more closely spaced due to negligible pollution.

The layout must be designed to minimize the capacitance at the SW node. Use as small an area of copper as possible to connect the device SW pin to the inductor, or transformer, or other output load. Furthermore, ensure that the ground plane or any other copper plane has a cutout so that there is no overlap with the SW node, as this would effectively form a capacitor on the printed circuit board. Additional capacitance on this node reduces the advantages of the advanced packaging approach of the LMG3100 and may result in reduced performance.

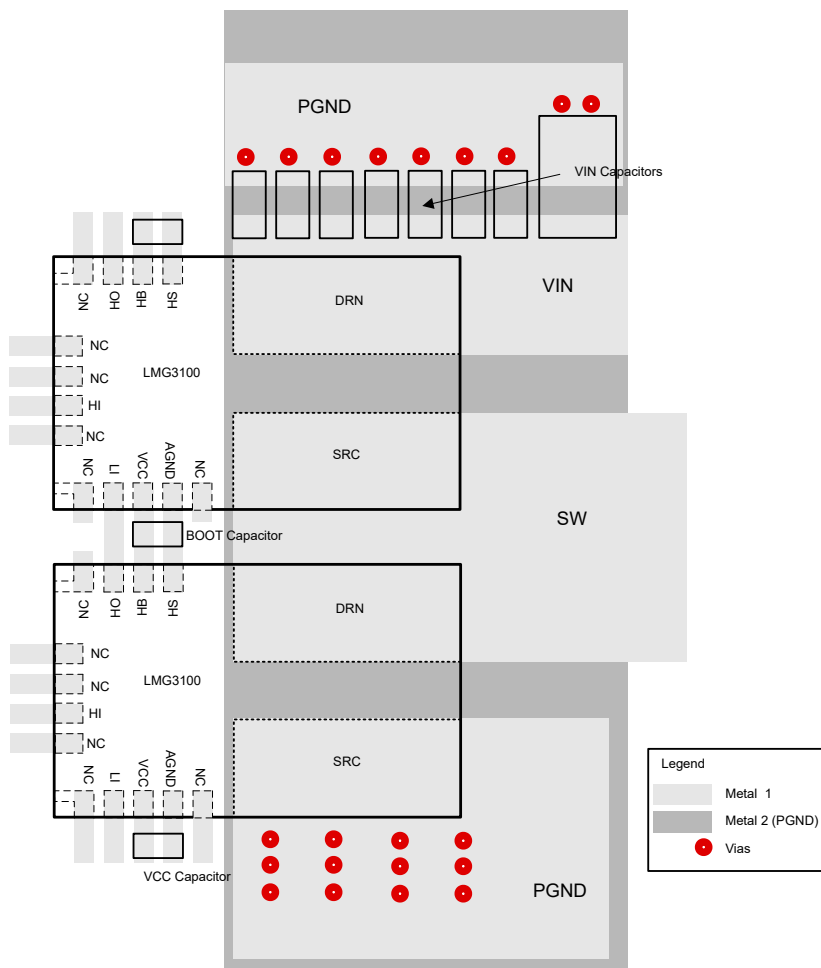


图 9-4. External Component Placement (Multi Layer Board)

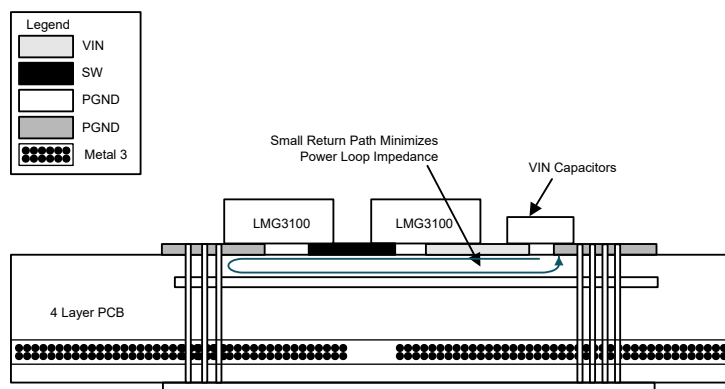


图 9-5. Four-Layer Board Cross Section With Return Path Directly Underneath for Power Loop

9 Device and Documentation Support

9.1 Documentation Support

9.1.1 Related Documentation

[Layout Guidelines for LMG3100 GaN Power Stage Module](#)

[Using the LMG3100: GaN Half-Bridge Power Module Evaluation Module](#)

9.2 接收文档更新通知

要接收文档更新通知，请导航至 [ti.com](https://www.ti.com) 上的器件产品文件夹。点击 [通知](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

9.3 支持资源

[TI E2E™ 中文支持论坛](#) 是工程师的重要参考资料，可直接从专家处获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题，获得所需的快速设计帮助。

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9.4 Trademarks

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9.6 术语表

TI 术语表

本术语表列出并解释了术语、首字母缩略词和定义。

10 Revision History

注：以前版本的页码可能与当前版本的页码不同

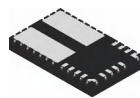
| DATE | REVISION | NOTES |
|--------------|----------|-----------------|
| January 2024 | * | Initial Release |

11 Mechanical, Packaging, and Orderable Information

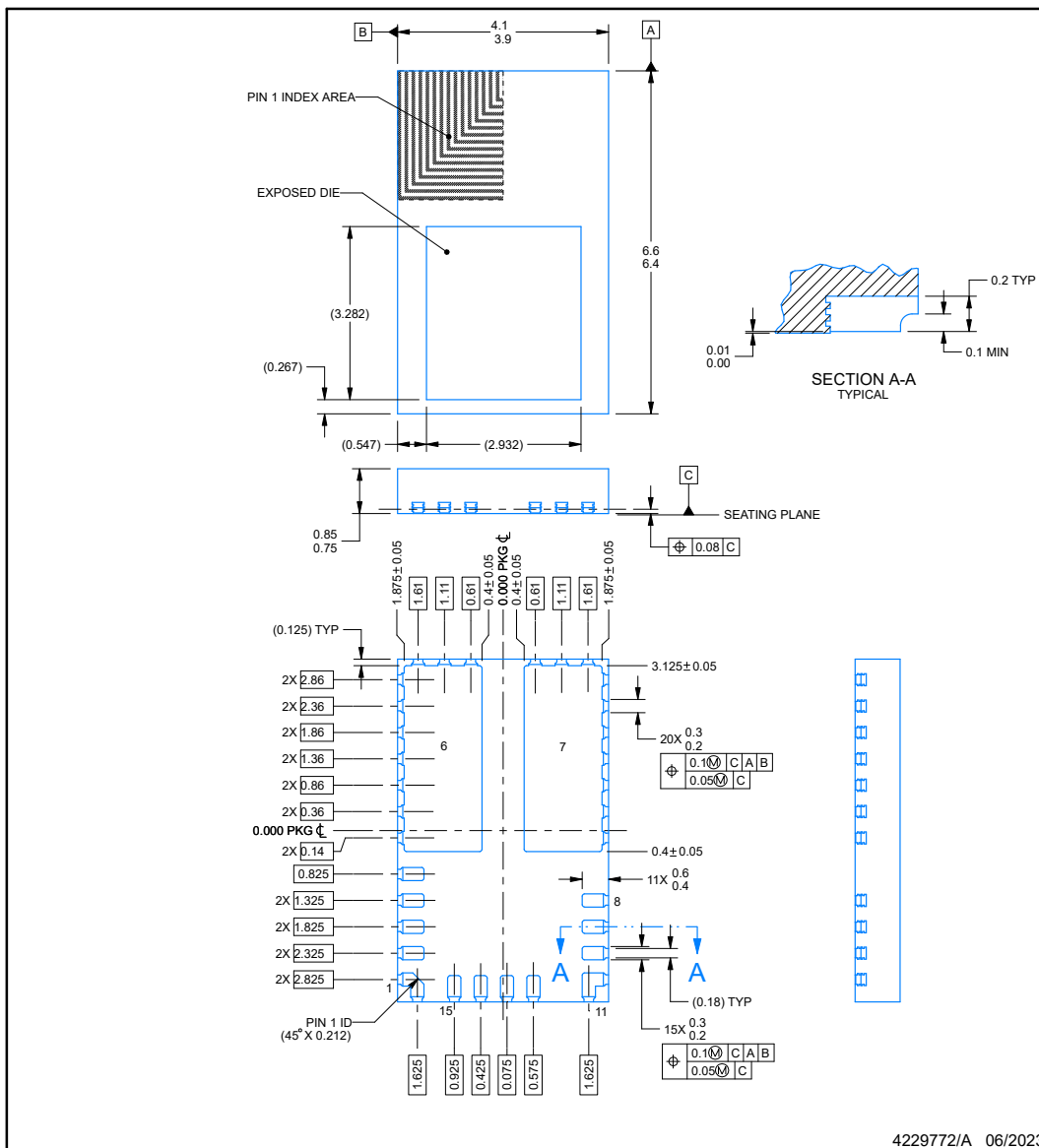
The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

11.1 Package Information

The LMG3100 device package is rated as an MSL3 package (Moisture Sensitivity Level 3). Refer to application report [AN-2029 Handling and Process Recommendations](#) for specific handling and process recommendations of an MSL3 package.

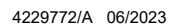
**PACKAGE OUTLINE****VBE0015A****VQFN-FCRLF - 0.85 mm max height**

PLASTIC QUAD FLATPACK - NO LEAD



EXAMPLE BOARD LAYOUT
VQFN-FCRLF - 0.85 mm max height

ADVANCE INFORMATION



4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

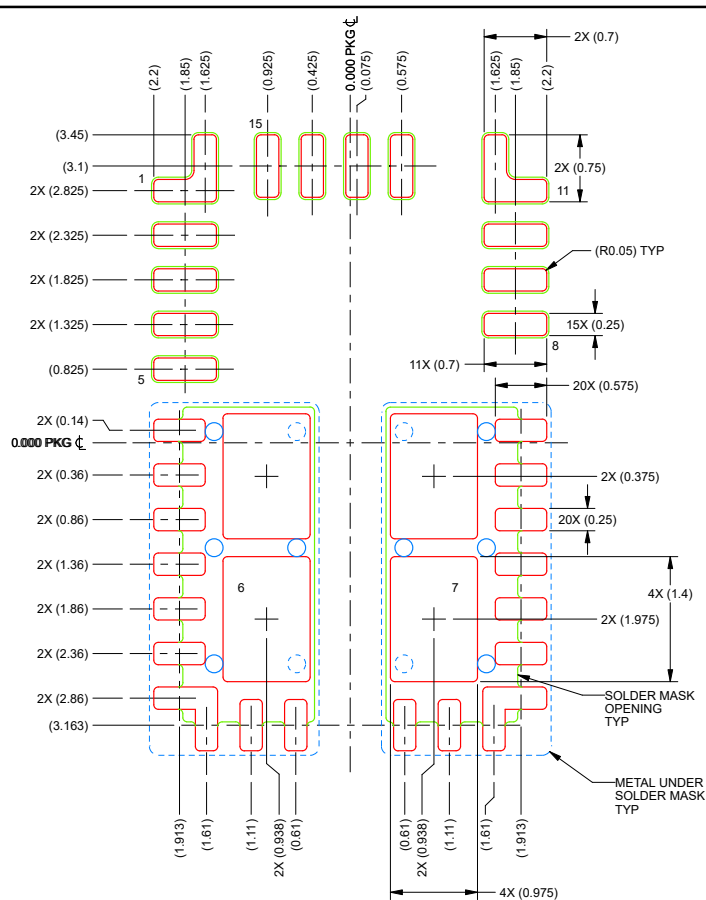
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

VBE0015A

VQFN-FCRLF - 0.85 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 15X

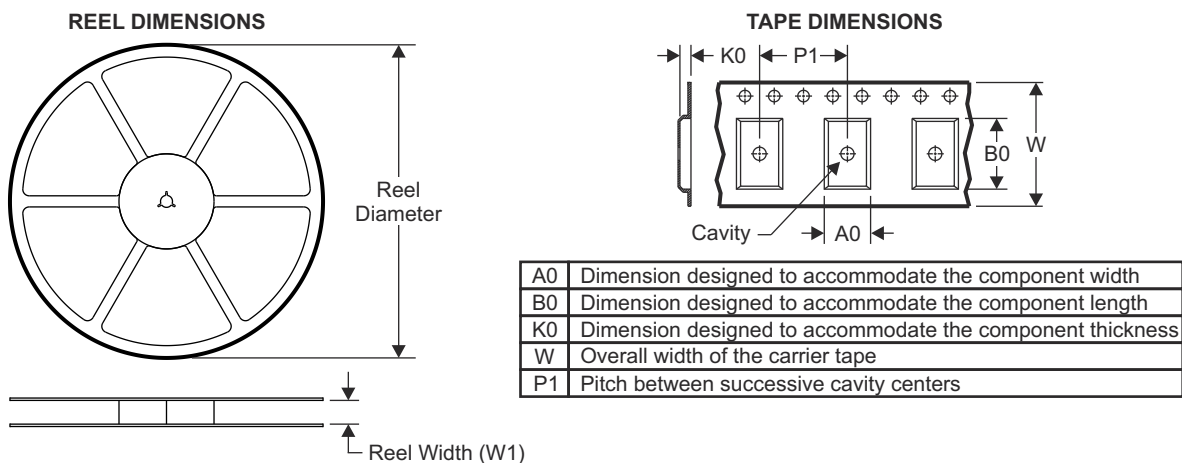
PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
PADS 6 & 7: 74%

4229772/A 06/2023

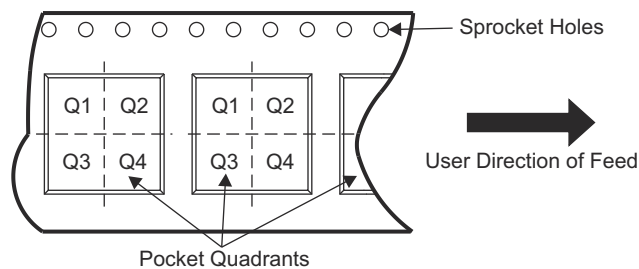
NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

11.2 Tape and Reel Information

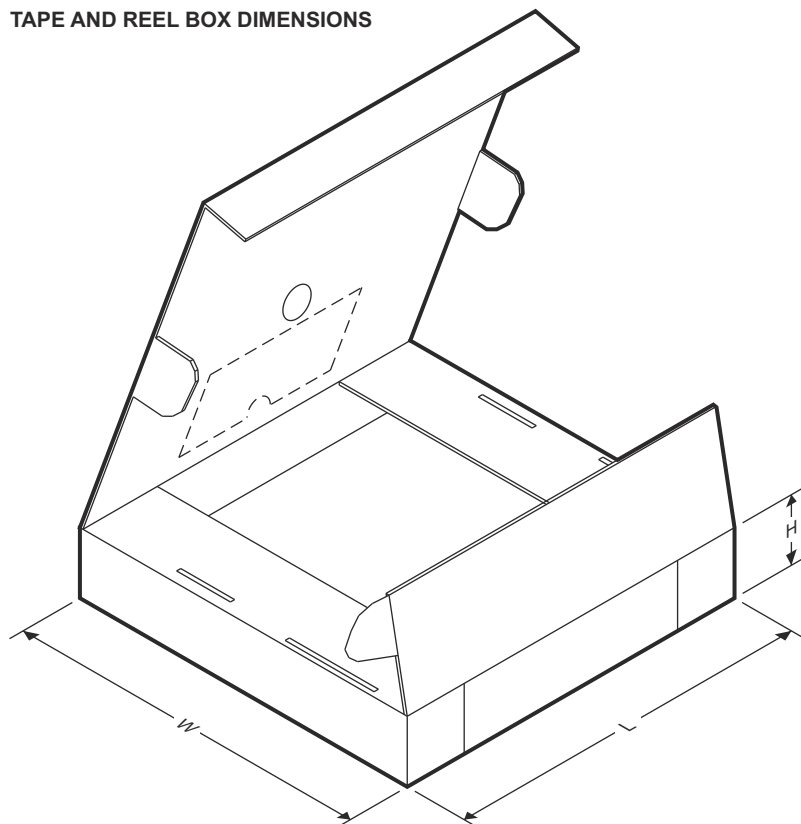


QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| LMG31000MOFT | QFM | MOF | 9 | 250 | 180 | 16.4 | 6.3 | 8.3 | 2.2 | 12.0 | 16.0 | Q1 |
| LMG31000MOFR | QFM | MOF | 9 | 2000 | 330 | 16.4 | 6.3 | 8.3 | 2.2 | 12.0 | 16.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| LMG31000MOFT | QFM | MOF | 9 | 250 | 213 | 191 | 55 |
| LMG31000MOFR | QFM | MOF | 9 | 2000 | 336.6 | 336.6 | 28.6 |

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|-----------------|--------------------------------------|----------------------|--------------|-------------------------|-------------------------|
| XLMG3100R017VBER | ACTIVE | VQFN-FCRLF | VBE | 15 | 2500 | TBD | Call TI | Call TI | -40 to 125 | | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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